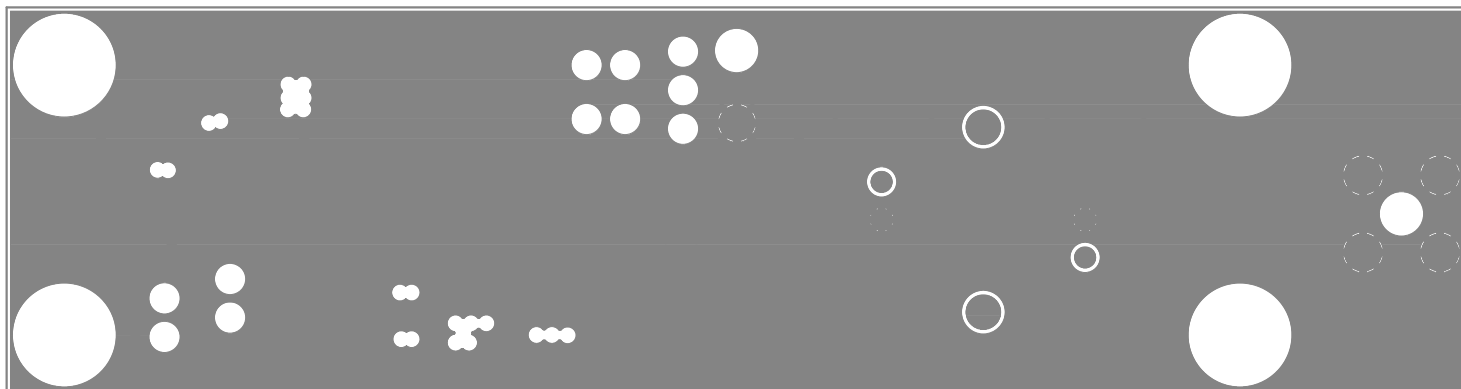
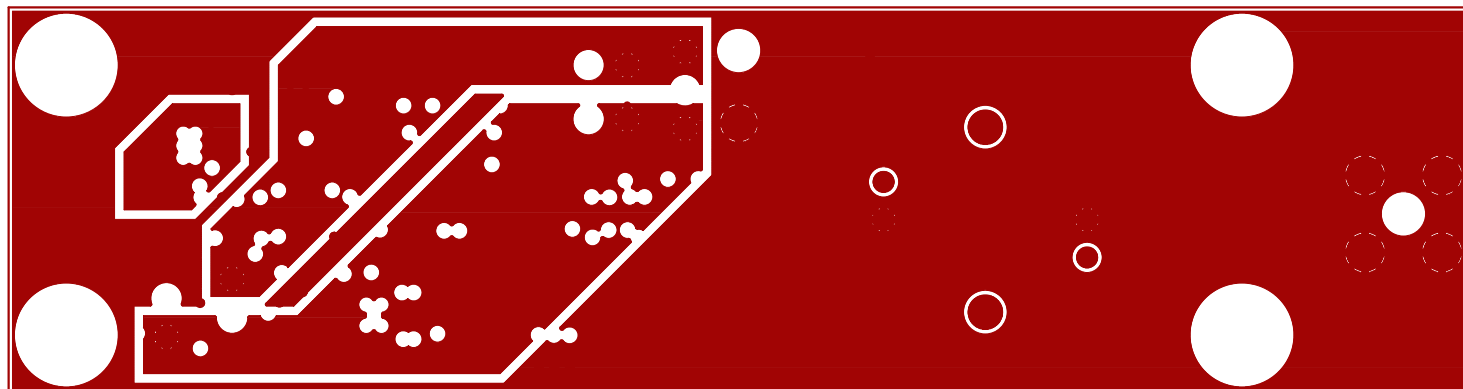


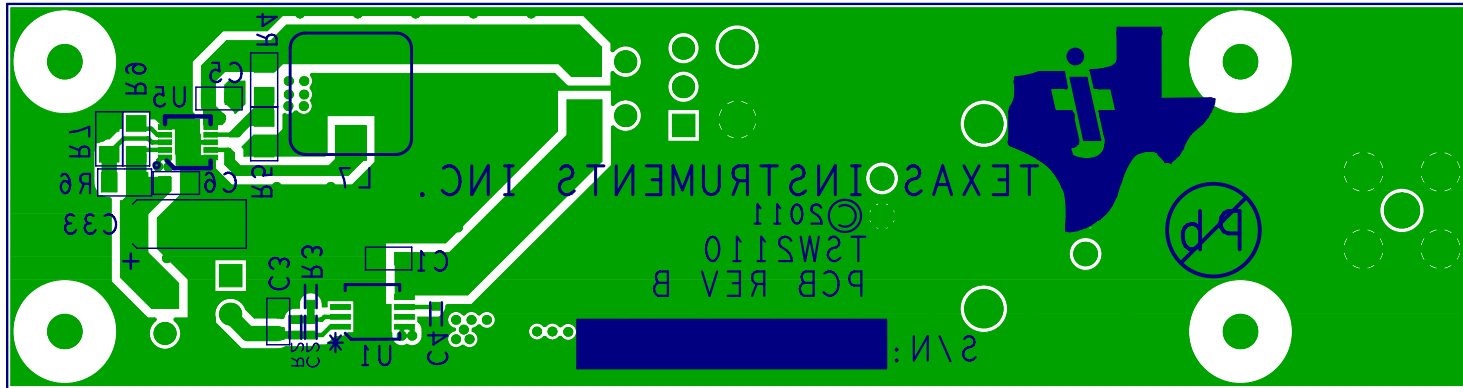
TEXAS INSTRUMENTS, INC.  
TSW2110 EVM  
PCB REV B  
SOLDERMASK TOP



TEXAS INSTRUMENTS, INC.  
TSW2110 EVM  
PCB REV B  
GROUND PLANE-LAYER 2



TEXAS INSTRUMENTS, INC.  
TSW2110 EVM  
PCB REV B  
POWER PLANE-LAYER 3



TEXAS INSTRUMENTS, INC.  
TSW2110 EVM  
PCB REV B  
SOLDSIDE BOTTOM

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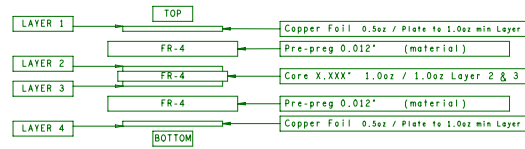
UNLESS OTHERWISE SPECIFIED, ALL NOTES ARE APPLICABLE.  
NOTES PRECEDED BY AN UNMARKED "□" ARE NOT APPLICABLE.

ZONE		LTR		REVISIONS		
				DESCRIPTION	DATE	APPROVED

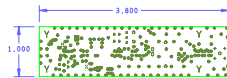
- APPLICATION DESIGN MANUFACTURING AND INSPECTION DOCUMENTS.  
IPC-2221A & IPC-2222 / DESIGN STANDARD FOR RIGID PRINTED CIRCUIT BOARDS AND RIGID PRINTED BOARD ASSEMBLIES  
IPC-6012B / QUALIFICATION AND PERFORMANCE SPECIFICATION FOR RIGID PRINTED BOARD  
IPC-A-600G / ACCEPTABILITY OF PRINTED BOARDS.
- HOLE SIZE APPLIES AFTER PLATING. TOLERANCE TO BE +/- .003.
- REGISTRATION TOLERANCE: ARTWORK +/- .002  
ALL HOLE CENTERS +/- .005 FROM DIMENSION DATUM.
- MINIMUM COPPER WALL THICKNESS SHALL BE .001 INCH.  
FOR ALL PLATED THROUGH HOLES. BREAKOUT NOT ALLOWED.
- PROCESS AND MATERIAL MUST CONFORM TO UL 796. MATERIAL MUST MEET OR EXCEED UL FLAMMABILITY RATING 94V-0.  
MATERIAL: □ SINGLE SIDED □ DOUBLE SIDED □ MULTI-LAYER (SEE DETAIL 'A')  
SEE LAYER STACKUP FOR ALL PRE-PREG & CORE THICKNESSES. COPPER OZ AND MATERIAL. FINISHED BOARD THICKNESS: 0.062 +/- .005
- MANUFACTURE'S UL MARKING, FLAMMABILITY RATING, LOGO AND DATE CODE TO BE PLACED IN SILKSCREEN ON BOTTOM SIDE OF THE BOARD.
- SOLDERMASK BOTH SIDES USING TAIYO (OR EQUIVALENT).  
COLOR: RED (0.001 TO 0.002" THICK OVER METAL).
- SILKSCREEN □ TOP SIDE □ BOTH SIDES, USING □ YELLOW □ WHITE NPT LEADFREE.  
REGISTRATION TOLERANCE TO BE +/- .005. INK IS NOT ALLOWED ON EXPOSED PLATED AREA.
- P.C. BOARD TO BE FREE OF DIRT, OIL, FINGER PRINTS, ETC.
- BOARD WARPAGE: WARP AND TWIST SHALL NOT EXCEED .007 INCH PER INCH.  
MEASURED AT ANY LOCATION OR DIRECTION ON THE BOARD.
- BOARD MUST BE 100% ELECTRICALLY TESTED TO ENSURE NO SHORTS OR OPEN CIRCUITS AT 20V.
- ALL INNER LAYER UNCONNECTED PADS SHALL BE REMOVED.

- ALL OUTER LAYERS USING A 20.00 mil TRACE WIDTH SHALL BE 50ohms SINGLE ENDED, +/- 10 TOLERANCE.  
□ ALL OUTER LAYERS USING A X.XX mil TRACE WIDTH SHALL BE 100ohms SINGLE ENDED, +/- 5% TOLERANCE.  
□ ALL INNER LAYERS USING A X.XX mil TRACE WIDTH SHALL BE 50ohms SINGLE ENDED, +/- 5% TOLERANCE.  
□ ALL INNER LAYERS USING A X.XX mil TRACE WIDTH SHALL BE 100ohms SINGLE ENDED, +/- 5% TOLERANCE.  
□ ALL OUTER LAYERS USING A X.XX mil TRACE WIDTH AND X.XX mil SPACING SHALL BE 100 ohms DIFFERENTIAL, +/- 5% TOLERANCE.  
□ ALL INNER LAYERS USING A X.XX mil TRACE WIDTH AND X.XX mil SPACING SHALL BE 100 ohms DIFFERENTIAL, +/- 5% TOLERANCE.
- MINIMUM COPPER CONDUCTOR WIDTH IS: .MIL.  
MINIMUM COPPER SPACING IS: .MIL.
- SMOBC/IMMERSION GOLD: 3-8 uIN OVER 100-200 uIN NICKEL PLATING.
- ALL THRU HOLE VIAS TO BE PLATED AND FILLED WITH NON-CONDUCTIVE EPOXY.  
FILLED VIAS SHALL BE PLATED AFTER FILLING AND COPLANAR.
- GROUND ETCH TO BOARD EDGE IS INTENTIONAL. DO NOT PULL BACK.
- NO CHANGES TO ANY ARTWORK ARE PERMITTED WITHOUT WRITTEN AUTHORIZATION.
- FINISHED BOARD MUST BE RoHS COMPLIANT AND SURVIVE A LEAD FREE ASSEMBLY.  
MAXIMUM REFLOW OF 260 DEGREES C (6 PASSES).
- BOARD TO BE PANELIZED FOR ASSEMBLY.

DETAIL 'A'



DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
-	10.0	PLATED	11
*	13.0	PLATED	214
o	32.0	PLATED	4
+	38.0	PLATED	11
o	62.0	PLATED	3
o	62.0	PLATED	2
-	67.0	PLATED	4
Y	125.0	NON-PLATED	4



TEXAS INSTRUMENTS, INC.  
1992117110  
PCB REV 0

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES +/- .XX +/- .01 +/- .XXX +/- .005 +/-	CONTRACT NO.		TEXAS INSTRUMENTS INC.	
	APPROVALS	DATE	FABRICATION DRAWING TSW2110 EVM	
DRAWN L. NGUYEN	07-22-11			
MATERIAL	ENGR J. NOVAK			
SEE NOTE 5				
FINISH	SEE NOTES 7, 8, 9			
DO NOT SCALE DRAWING	SIZE B	CODE IDENT NO.	DRAWING NO.	REV. B
	SCALE NONE			SHEET 1 OF 1

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